

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Aplinov	07/21/2010
RECEIVING PARTY DATA	
Name:	S.O.I. Tec Silicon on Insulator Technologies
Street Address:	Chemin des Franques
Internal Address:	Parc Technologique des Fontaines
City:	Bernin
State/Country:	FRANCE
Postal Code:	38190
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11628185
CORRESPONDENCE DATA	
Fax Number:	(512)853-8801
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Email:	jpitre@intprop.com
Correspondent Name:	Jackie Pitre
Address Line 1:	700 Lavaca
Address Line 2:	Suite 800
Address Line 4:	Austin, TEXAS 78701
ATTORNEY DOCKET NUMBER:	6420-00100
NAME OF SUBMITTER:	Eric B. Meyertons
Total Attachments: 3 source=Assignment Agreement_11628185#page1.tif source=Assignment Agreement_11628185#page2.tif source=Assignment Agreement_11628185#page3.tif	

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PATENT
REEL: 025636 FRAME: 0882

ASSIGNMENT AGREEMENT

This Agreement is entered into by and between Aplinov, having a place of business at 9 Presvert, 38113 Veurey-Voroize, France and S.O.I. Tec Silicon on Insulator Technologies, having a place of business at Chemin des Franques, Parc Technologique des Fontaines, 38190 Bernin, France.

In consideration of the mutual agreements contained herein and for other good and valuable consideration, acknowledged by each of them to be satisfactory and adequate, the parties hereby agree as follows:

1. Aplinov hereby assigns to S.O.I. Tec Silicon on Insulator Technologies the entire right, title and interest in the United States in and to any and all improvements and/or inventions which are disclosed in United States Letters Patent Application Serial No. 11/628,185 filed on November 4, 2008, and which is entitled "**METHOD FOR PRODUCING A MULTILAYER STRUCTURE COMPRISING A SEPARATING LAYER**", such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and/or any other countries on any of such improvements and/or inventions; all original and reissued patents which have been or shall be issued in the United States and/or any other countries on such improvements and/or inventions; and specifically including the right to file applications in any other countries under the provisions of any convention or treaty and claim priority based on such applications in the United States and/or any other countries.
2. Aplinov hereby authorizes and requests any issuing authority to issue to S.O.I. Tec Silicon on Insulator Technologies any and all United States patents granted on the above-referenced improvements and/or inventions, including the patent application identified above and any subsequent applications filed in the United States and/or any other countries for the improvements and/or inventions.
3. Aplinov hereby warrants that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned.
4. Aplinov hereby agrees that, when requested and at the expense of S.O.I. Tec Silicon on Insulator Technologies, to carry out in good faith the intent and purpose of this assignment, that Aplinov will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements and/or inventions; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to S.O.I. Tec Silicon on Insulator Technologies all facts known to the undersigned relating to such improvements and/or inventions and the history thereof; and generally do everything possible which S.O.I. Tec Silicon on Insulator Technologies shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and/or inventions and for vesting title to such improvements and/or inventions in S.O.I. Tec Silicon on Insulator Technologies.

5. S.O.I. Tec Silicon on Insulator Technologies shall have the sole right to institute, prosecute and control actions, suits or proceedings ("Actions") against third parties with respect to any past, present, or future infringement of any patents maturing from the above-referenced applications, including any declaratory judgment actions, at its expense, using counsel of its choice. Any receipts from such an Actions, including, but not limited to, awards or settlement payments, shall belong to S.O.I. Tec Silicon on Insulator Technologies.

6. This Agreement is binding on the assigns, representatives, and successors of both Aplinov and S.O.I. Tec Silicon on Insulator Technologies.

IN WITNESS WHEREOF, the parties hereto have executed this Agreement as follows:

APLINOV

Signature: _____
Print Name: MICHEL BRUEL
Title: CEO
Date: 26th July 2010

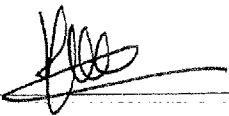
Emmanuel HUYGHE
(Witness) [Signature]

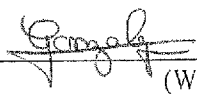
Date: 21st July 2010

Gonzalez
(Witness) Anto GONZALEZ

Date: 21st July 2010

S.O.I. TEC SILICON ON INSULATOR TECHNOLOGIES

Signature: 
Print Name: EMMANUEL HUYGHE
Title: JP Director
Date: 21 / 07 / 2010

 Anita GONZALEZ Date: 27 st July 2010
(Witness)

Chaitrejean Esther Naitrejean Date: 21st July 2010
(Witness)